



MULTILAYER CERAMIC CAPACITORS

Capacitor Arrays Series (10V to 100V)

4 x 0402, 4 x 0603 Sizes

NP0, X7R & Y5V Dielectrics

Halogen Free & RoHS Compliance

*Contents in this sheet are subject to change without prior notice.



1. INTRODUCTION

WTC middle and high voltage series MLCC is designed by a special internal electrode pattern, which can reduce voltage concentrations by distributing voltage gradients throughout the entire capacitor. This special design also affords increased capacitance values in a given case size and voltage rating.

WTC capacitor arrays are developed to offer designers the opportunity to lower placement costs increase assembly line output through lower component count per board.

2. FEATURES

- a. High density mounting due to mounting space saving.
- b. Mounting cost saving.
- c. Increased throughput.

3. APPLICATIONS

- a. For use as a bypass for digital and analog signal line noise
- b. Computer motherboards and peripherals.
- c. The other common electronic circuits.

4. HOW TO ORDER

<u>Y</u>	<u>4C</u>	<u>3</u>		B	<u>103</u>	K	<u>500</u>	<u>C</u>	Ī		
<u>Series</u>	Cap. Nr.	Termination pitch		Termination pitch		Dielectric	<u>Capacitance</u>	Tolerance	Rated voltage	Termination	Packaging
			1	$\sum x$	X	<i>Z //</i> /> ~	Fri				
Y=Capacitor	4C =4xCap	3 =0.03" pitch*	117	N=NP0	Two significant	J =±5%	Two significant	C =Cu/Ni/Sn	T=7" reeled		
array		2=0.02" pitch*		(C0G)	digits followed	K =±10%	digits followed				
				B =X7R	by no. of zeros.	M =±20%	by no. of zeros.				
				F=Y5V	And R is in	Z =-20/+80%	And R is in				
	I		8		place of	LLIANCE	place of decimal				
	//C3· /v060	3 (0612)	R	3	decimal point.		point.				
	403. 4000	5 (0012) 5 (0595)	6	3 5.			52				
ľ	4C2: 4X040	2 (0508)	12	0, 0,	eg.:		eg.:				
				Mar .	103=10x10 ³	CON	100=10 VDC				
				SINT.	=10,000pF		160=16 VDC				
				120	//=10nF	RATION	250=25 VDC				
					UCLUGI LUKP		500=50 VDC				
							101 =100 VDC				

*Size/ Inch (mm) : 4x0402=0508 (1220), 4x0603=0612 (1632)



5. EXTERNAL DIMENSIONS



Size Inch (mm)	L (mm)	W (mm) T (mm)/Symbol		S (mm)	BW (mm)	P (mm)	
4x0402 0508 (1220)	2.00±0.15	1.25±0.15	0.85±0.10	Т	0.20±0.10	0.25±0.10	0.50±0.10
4x0603 0612 (1632)	3.20±0.15	1.60±0.15	0.80±0.10	В	0.30±0.20	0.40±0.15	0.80±0.15

Reflow soldering process only.

6. GENERAL ELECTRICAL DATA

	144111							
Dielectric	, NI	P0	X7	Y5V				
Size	4x0402	4x0603	4x0402 4x0603		4x0603			
Inch (mm)	0508 (1220)	0612 (1632)	0508 (1220)	0612 (1632)	0612 (1632)			
Capacitance*	10pF to 270pF	=10pF to 470pF	1000pF to 100nF	150pF to 100nF	10nF to 100nF			
Capacitance tolerance**	J (±5%),	K (±10%)	K (±10%),	Z (-20/+80%)				
Rated voltage (WVDC)	25, 50	V, 100V	10V, 16V, 25V, 50V	16V, 50V				
Q/Tan δ*	Cap<30pF: Cap≥30pF	Q≥400+20C =: Q≥1000	Ur=50V Ur=25V&1 Ur=10V	Ur=50V, ≤5% Ur=16V, ≤7%				
Insulation resistance at Ur	≥10	GOLANDION	≥10GΩ (or RxC≥500ΩxF whic	chever is less			
Operating temperature		-55 to) +125℃	-25 to +85℃				
Capacitance characteristic ±30ppm			±1;	+30/-80%				
Termination	Ni/Sn (lead-free termination)							

* Measured at 30~70% related humidity.

NP0: Apply 1.0±0.2Vrms, 1.0MHz±10% at the conditions of 25°C ambient temperature.

X7R: Apply 1.0±0.2Vrms, 1.0kHz±10%, at the conditions of 25℃ ambient temperature.

Y5V: Apply 1.0±0.2Vrms, 1.0kHz±10%, at the conditions of 20℃ ambient temperature.

** Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in a mbient condition for 24±2 hours before measurement.

Approval Sheet

7. CAPACITANCE RANGE

	SIZE Inch (mm)			C	4 x 040 0508 (12	02 220)			4x0603 0612 (1632)							
DIELECTRIC			NP0			X	7R		NP0 X7R			Y	5V			
RAT	ED VOLTAGE (VDC)	25	50	100	10	16	25	50	25	50	100	16	25	50	16	50
	10pF (100)	Т	Т	Т					В	В	В					
	15pF (150)	Т	Т	Т					В	В	В					
	22pF (220)	Т	Т	Т					В	В	В					
	33pF (330)	Т	Т	Т					В	В	В					
	47pF (470)	Т	Т	Т					В	В	В					
	68pF (680)	Т	Т	Т					В	В	В					
	100pF (101)	Т	Т	Т					В	В	В					
	120pF (121)	Т	Т	Т					В	В	В					
	150pF (151)	Т	Т	Т					В	В	В		В	В		
	180pF (181)	Т	Т	Т					В	В	В		В	В		
	220pF (221)	Т	Т	Т					В	В	В		В	В		
	270pF (271)	Т	Т	Т					В	В	В		В	В		
JCe	330pF (331)								В	В	В		В	В		
itar	470pF (471)								В	В	В		В	В		
pac	6,80pF (681)												В	В		
Ca	1,000pF (102)				Т	Т	27	ÉΤ	13				В	В		
	1,500pF (152)				Т	<u>JE</u>	PT	Т	R	SE.			В	В		
	2,200pF (222)				Т	<u>T</u>	J.	阳小	\rightarrow X	1.	1		В	В		
	3,300pF (332)				T, N	<u>, Х</u> Т 4,	<u>}ĭ></u>	T-	$\langle \mathcal{A} \rangle$		Ta		В	В		
	4,700pF (472)				17.17		Ť	Т		<i>?</i> —	72		В	В		
	6,800pF (682)				f~	$\mu \tilde{T}$	Т	Т			2		В	В		
	0.010µF (103)				Т	'ᡤ	I	T			Δ		В	В		В
	0.015µF (153)				Т	Т	Т	N	A			В	В	В		В
	0.022µF (223)				g	T PA	ssive	SYSTEM	ALLIA	NCE	- 0	В	В	В		В
	0.033µF (333)				Y	ZT \	Т			. C		В				В
	0.047µF (473)				る	T	Т				22	В				В
	0.068µF (683)				T	T (Т			0	S	В				В
	0.10µF (104)				Т	T	6		60	2.4	5	В			В	В

1. The letter in cell is expressed the symbol of product thickness.

8. PACKAGING DIMENSION AND QUANTITY

SIZE	Thickness/Syn	nbol	Paper tape			
Inch (mm)	(mm)		7" reel	13" reel		
4x0402 0508 (1220)	0.85±0.10	т	4k	-		
4x0603 0612 (1632)	0.80±0.10	В	4k	-		

Unit: pieces



9. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	ltem	Test Condition	Requirements				
1.	Visual and		* No remarkable defect.				
	Mechanical		* Dimensions to conform to individual specification sheet.				
2.	Capacitance	Class I: (NP0)	* Shall not exceed the limits given in the detailed spec.				
3.	Q/ D.F.	1.0±0.2Vrms, 1MHz±10%	NP0: Cap≥30pF Q≥1000: Cap<30pF Q≥400+20C				
	(Dissipation	Class II: (X7R, Y5V)	X7R: Ur=50V, ≤2.5%; Ur=25V&16V, ≤3.5%; Ur=10V, ≤5.0%				
	Factor)	1.0±0.2Vrms, 1kHz±10%	Y5V: Ur=50V <5%; Ur=16V <7%				
	,	*Before initial measurement (Class II only): To apply de-aging					
		at 150°C for 1hr then set for 24±2 hrs at room temp.					
4.	Dielectric	* To apply 250% rated voltage.	* No evidence of damage or flash over during test.				
	Strength	* Duration: 1 to 5 sec.					
	-	* Charge and discharge current less than 50mA.					
5.	Insulation	To apply rated voltage for max. 120 sec.	≥10G Ω or RxC≥500 Ω -F whichever is smaller.				
	Resistance	*Before initial measurement (Class II only): To apply de-aging					
		at 150°C for 1hr then set for 24±2 hrs at room temp.					
6.	Temperature	With no electrical load.					
	Coefficient	T.C. Operating Temp	T.C. Capacitance Change				
		NP0 -55~125℃ at 25℃	NP0 Within ±30ppm/℃				
		X7R -55~125°C at 25°C	X7R Within ±15%				
		175V	Y5V Within +30%/-80%				
		"Before initial measurement (Class II only): To apply de-aging					
7		at 150°C for 1nr then set for 24±2 hrs at room temp					
1.	Adhesive	Pressurizing force	No remarkable damage or removal of the terminations.				
	Strength of	5N (\$0603) and 10N (>0603)					
0	Vibratian	test time: To±1 sec.	* Na samadahla damasa				
ο.	Vibration	* Vibration frequency: 10~55 Hz/min.	No remarkable damage.				
	Resistance		Cap change and GD.F. To meet mitial spec.				
		nest time: 6 his. (1 wo his each in three mutually					
		*Perfere initial macaurement (Class II only): To apply do aging					
		at 150°C for 1br than set for 24-2 brs at room temp					
		*Cap $(DE(O))$ Moacurement to be made after do aging at 150°C	0, 1, 199				
		for the then set for 24+2 hrs at room terms	TON ALL				
Q	Soldorability	* Solder temperature: 225+59	05% min. coverage of all motolized area				
5.	Solderability	* Dipping time: 2+0.5 sec	3078 mm. coverage of an metalized area.				
10	Bending Test	* The middle part of substrate shall be pressurized by means	* No remarkable damage				
10.	Denuing rest	of the pressurizing rod at a rate of about 1 mm per second until	ili* Can change :				
		the deflection becomes 1 mm and then the pressure shall be	NP0: within +5 0% or +0 5nE whichever is larger				
		maintained for 5+1 sec	X7R: within ±12.5%				
		*Before initial measurement (Class II only): To apply de-aging	X/R. Within ±12.5%				
		at 150°C for 1hr then set for 24±2 hrs at room temp	(This canacitance change means the change of capacitance under				
		*Measurement to be made after keeping at room temp, for	specified flexure of substrate from the capacitance measured before				
		24±2 hrs.	the test.)				
11.	Resistance to	* Solder temperature: 260±5℃	* No remarkable damage.				
	Soldering Heat	* Dipping time: 10±1 sec	* Cap change:				
		* Preheating: 120 to 150°C for 1 minute before immerse the	NP0: within ±2.5% or ±0.25pF whichever is larger.				
		capacitor in a eutectic solder.	X7R: within ±7.5%				
		*Before initial measurement (Class II only): To apply de-aging	Y5V: within ±20%				
		at 150°C for 1hr then set for 24±2 hrs at room temp.	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.				
		*Cap. / DF(Q) / I.R. Measurement to be made after de-aging at	* 25% max. leaching on each edge.				
		150℃ for 1hr then set for 24±2 hrs at room temp.					



No.	ltem	Test Condition	Requirements				
12.	Temperature	* Conduct the five cycles according to the temperatures and	No remarkable damage.				
	Cycle	time.	* Cap change :				
		Step Temp. (°C) Time (min.)	NP0: within $\pm 2.5\%$ or ± 0.25 pF whichever is larger.				
		1 Min. operating temp. +0/-3 30±3	X7R: within ±7.5%				
		2 Room temp. 2~3	Y5V: within ±20%				
		3 Max. operating temp. +3/-0 30±3	* Q/D.F., I.R. and dielectric strength: To meet initial requirements.				
		4 Room temp. 2~3					
		*Before initial measurement (Class II only): To apply de-aging					
		at 150°C for 1hr then set for 24±2 hrs at room temp.					
		* Cap. / DF(Q) / I.R. Measurement to be made after de-aging					
		at 150°C for 1hr then set for 24±2 hrs at room temp.					
13.	Humidity	* Test temp.: 40±2℃					
	(Damp Heat)	* Humidity: 90~95% RH	No remarkable damage.				
	Steady State	* Test time: 500+24/-0hrs.	Cap change: NP0: within $\pm 5.0\%$ or ± 0.5 pF whichever is larger.				
		*Before initial measurement (Class II only): To apply de-aging	X7R: within ±12.5%				
		at 150℃ for 1hr then set for 24±2 hrs at room temp.	Y5V: within ±30%				
		* Cap. / DF(Q) / I.R. Measurement to be made after de-aging	* Q/D.F. value:				
		at 150°C for 1hr then set for 24 ± 2 hrs at room temp .	NP0: Cap≥30pF, Q≥350; 10pF≤Cap<30pF, Q≥275+2.5C				
			Cap<10pF; Q≥200+10C				
		水石 1	X7R: Ur=50V, ≤3%; Ur=25V&16V, ≤5%; Ur=10V, ≤7.5%				
		HE PILE	Y5V: Ur=50V, ≤7.5%; Ur=16V, ≤10%				
		长 下,	* I.R.:≥1GΩ or RxC≥50Ω-F whichever is smaller.				
14.	Humidity	* Test temp.: 40±2℃	* No remarkable damage.				
	(Damp Heat)	* Humidity: 90~95%RH	* Cap change: NP0: within ±7.5% or ±0.75pF whichever is larger.				
	Load	* Test time: 500+24/-0 hrs.	X7R: within ±12.5%				
		* To apply voltage : rated voltage.	Y5V: within ±30%				
		*Before initial measurement (Class II only): To apply de-aging	* Q/D.F. value:				
		at 150°C for 1hr then set for 24±2 hrs at room temp.	NP0: Cap≥30pF, Q≥200; Cap<30pF, Q≥100+10/3C				
		* Cap. / DF(Q) / I.R. Measurement to be made after de-aging	X7R: Ur=50V, ≤3%; Ur=25V&16V, ≤5%; Ur=10V, ≤7.5%				
		at 150°C for 1hr then set for 24±2 hrs at room temp.	Y5V: Ur=50V, ≤7.5%; Ur=16V, ≤10%				
		Ch ? x	* I.R.: ≥500MΩ or RxC≥25Ω-F whichever is smaller.				
15.	High	* Test temp.:	* No remarkable damage.				
	Temperature	NP0, X7R: 125±3℃	* Cap change: NP0: within $\pm 3.0\%$ or ± 0.3 pF whichever is larger.				
	Load	Y5V: 85±3℃	X7R: within ±12.5%				
	(Endurance)	* To apply voltage: 200% of rated voltage.	Y5V: within ±30%				
		* Test time: 1000+24/-0 hrs.	* Q/D.F. value:				
		*Before initial measurement (Class II only): To apply de-aging	NP0: Cap≥30pF, Q≥350				
		at 150°C for 1hr then set for 24 \pm 2 hrs at room temp .	10pF≤Cap<30pF, Q≥275+2.5C				
		* Cap. / DF(Q) / I.R. Measurement to be made after de-aging	Cap<10pF, Q≥200+10C				
		at 150°C for 1hr then set for 24 \pm 2 hrs at room temp .	X7R: Ur=50V, ≤3%; Ur=25V&16V, ≤5%; Ur=10V, ≤7.5%				
			Y5V: Ur=50V, ≤7.5%; Ur=16V, ≤10%				
			* I.R.: ≥1GΩ or RxC≥50Ω-F whichever is smaller.				

Copyright © by Walsin Technology Corporation. | All rights reserved.

APPENDIXES

Tape & reel dimensions



Approval Sheet

Constructions

No.	Nam	ne	NP0, X7R, Y5V
1	Ceramic r	naterial	BaTiO₃ based
2	Inner ele	ctrode	Ni
3		Inner layer	Cu
4	Termination	Middle layer	Ni
5		Outer layer	Sn (Matt)



Storage and handling conditions

- (1) To store products at 5 to 40°C ambient temperature and 20 to 70%. related humidity conditions.
- (2) The product is recommended to be used within one year after shipment. Check solderability in case of shelf life extension is needed.

Cautions:

- a. The corrosive gas reacts on the terminal electrodes of capacitors, and results in the poor solderability. Do not store the capacitors in the ambience of corrosive gas (e.g., hydrogen sulfide, sulfur dioxide, chlorine, ammonia gas etc.)
- b. In corrosive atmosphere, solderability might be degraded, and silver migration might occur to cause low reliability.
- c. Due to the dewing by rapid humidity change, or the photochemical change of the terminal electrode by direct sunlight, the solderability and electrical performance may deteriorate. Do not store capacitors under direct sunlight or dewing condition. To store products on the shelf and avoid exposure to moisture.

Recommended soldering conditions

The lead-free termination MLCCs are not only to be used on SMT against lead-free solder paste, but also suitable against lead-containing solder paste. If the optimized solder joint is requested, increasing soldering time, temperature and concentration of N₂ within oven are recommended.





Copyright © by Walsin Technology Corporation. | All rights reserved.



X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Capacitor Arrays & Networks category:

Click to view products by Walsin manufacturer:

Other Similar products are found below :

CA064C473M4RACTU 20109D1X102K5P CKCL22X5R0J105M W2L16C473MAT1S W2L16C683MAT1A C1632C103M5RACAUTO CA064C223K5RACTU CA064C473K4RACTU Y4C3B104K160CT CKCM25X5R1A473M CKCM25X5R0J105M 20608TC750G331KP CA064C221M5GACTU CA064C471M3GACTU W2L16C474MAT1A CA064C100K5GACTU W2L14Z225MAT1A W2L1YC104MAT1F CA0508KRNPO9BN101 CA0508KRNPO9BN470 CA0612JRNPO9BN221 CA0612KRNPO9BN151 CA0612KRX7R9BB103 CA064C103M5RACTU CA064C223K5RAC7800 CA064C330K5GACTU CA064C472K5RACTU LG224Z224MAT2S1 20108D1X103K5E W3A45C102M4T2A CA064C103K4RACTU CA064C222K5RACTU CA0612KRNPO9BN101 CA0612KRX7R7BB473 CA0612KRX7R9BB102 CA064C103K5RACTU CA064C104K4RACTU C1632C223M5RAC3020 CA0612JRNPO9BN470 CA0612KRNPO9BN181 CA064C101K5GACTU CA064C102K5RACTU 20115D1C271K5P W3A45A151KAT2A CKCL22JB1H102M085AA W3A41C471KAT2A CKCL22C0G1H221K085AK CKCM25C0G2A220K060AK CKCL22CH1H151K085AA W3A41A470JAT2A